

Title (en)

Process for obtaining a metallic composite band

Title (de)

Verfahren zur Herstellung eines metallischen Verbundbands

Title (fr)

Procédé pour obtenir une bande composite métallique

Publication

**EP 0919644 B1 20020220 (DE)**

Application

**EP 98121473 A 19981111**

Priority

DE 19752329 A 19971126

Abstract (en)

[origin: US2001004048A1] A method for manufacturing a metal composite strip for the production of electrical contact components. A film made of tin or a tin alloy is first applied onto an initial material made of an electrically conductive base material. A film of silver is then deposited thereonto. Copper or a copper alloy is preferably used as the base material. The tin film can be applied in the molten state, and the silver film by electroplating. Furthermore, both the tin film and the silver film can be deposited by electroplating. A further alternative provides for manufacturing the tin film in the molten state and the silver film by cathodic sputtering. The diffusion operations which occur in the coating result in a homogeneous film of a tin-silver alloy. This formation can be assisted by way of a heat treatment of the composite strip.

IPC 1-7

**C23C 28/02**; **C23C 14/16**; **C25D 3/30**; **C25D 3/46**

IPC 8 full level

**C23C 2/08** (2006.01); **C23C 2/08** (2006.01); **C23C 14/16** (2006.01); **C23C 14/58** (2006.01); **C23C 28/02** (2006.01); **C25D 3/30** (2006.01); **C25D 3/46** (2006.01); **C25D 7/00** (2006.01); **H01R 13/03** (2006.01)

CPC (source: EP KR US)

**C23C 2/08** (2013.01 - EP US); **C23C 2/26** (2013.01 - EP KR US); **C23C 2/40** (2013.01 - EP US); **C23C 28/00** (2013.01 - KR); **C23C 28/021** (2013.01 - EP US); **C23C 28/023** (2013.01 - EP US); **C25D 3/30** (2013.01 - EP US); **C25D 3/46** (2013.01 - EP US)

Cited by

DE102012017520A1; US9592533B2; WO2022073575A1

Designated contracting state (EPC)

AT BE CH DE DK ES FI FR GB GR IE IT LI LU NL PT SE

DOCDB simple family (publication)

**US 2001004048 A1 20010621**; **US 6495001 B2 20021217**; AT E213508 T1 20020315; DE 19752329 A1 19990527; DE 59803128 D1 20020328; DK 0919644 T3 20020610; EP 0919644 A1 19990602; EP 0919644 B1 20020220; ES 2172851 T3 20021001; JP H11222659 A 19990817; KR 19990045402 A 19990625; PT 919644 E 20020731; US 6207035 B1 20010327

DOCDB simple family (application)

**US 77414601 A 20010130**; AT 98121473 T 19981111; DE 19752329 A 19971126; DE 59803128 T 19981111; DK 98121473 T 19981111; EP 98121473 A 19981111; ES 98121473 T 19981111; JP 32846898 A 19981118; KR 19980049669 A 19981119; PT 98121473 T 19981111; US 19668498 A 19981120